



# Product Change Notification

**Change Notification #:** 116786 - 00  
**Change Title:** Intel® RAID Module RMSP3AD160F, PCN 116786-00, Product Design, Resistor change and firmware update  
**Date of Publication:** February 27, 2019

## Key Characteristics of the Change:

Product Design

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material:*</b>	March 15, 2019
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\*Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

## Description of Change to the Customer:

Intel is implementing the following changes on the Intel® RAID Module RMSP3AD160F:

1. Change in resistor placement in the memory voltage regulator circuit order to allow 1.8V NOR flash memory. This is to allow a second source memory vendor.
2. Remove pull-up resistor in the Supercap charge circuit to increase charge circuit margin.
3. Update the firmware to version 5.050.00-1367 (MR 7.5p2 on firmware package 50.5.2-1326)

## Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from this change. Customers may need to validate the function and feature change once the post-change system is available.

## Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
RMSP3AD160F	954552	J25668-004	J25669-202	J25668-005	J25669-203

## PCN Revision History:

<b>Date of Revision:</b>	<b>Revision Number:</b>	<b>Reason:</b>
February 27, 2019	00	Originally Published PCN



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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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